Product Change Notification: MFOL-30OMBY736

Date:

23-Oct-2025

Product Category:

Ethernet Phys

Notification Subject:

CCB 7393 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8051 and KSZ8081 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Affected CPNs:

MFOL-30OMBY736_Affected_CPN_10232025.pdf
MFOL-30OMBY736_Affected_CPN_10232025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8051 and KSZ8081 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes

Die Attach Material	3280	3280NP	Yes
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 November 2025 (date code: 2548)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025					>	**October 2025**					**November 2025**				
Work Week	05	06	07	08	09		40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date		x														
Qual Report Availability										x						
Final PCN Issue Date										x						
Estimated Implementation Date															x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 04, 2025: Issued initial notification.
October 23, 2025. Issued final notification. Updated notification subject to remove KSZ8091 device family. Updated affected parts list to remove KSZ8081MNXCA, KSZ8081MNXIA, KSZ8091MNXCA, KSZ8091RNBCA, SPNZ801174, KSZ8081RNBCA-TR, KSZ8091RNBCA-TR, KSZ8081MNXCA-TR, KSZ8091MNXCA-TR, KSZ8091MNXIA-TR and KSZ8091RNBIA-TR catalog part numbers. Added a new column titled 'Change (Yes/No)' to the Pre and Post Change Summary table. Attached the qualification report. Provided estimated first ship date to be on November 24, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-30OMBY736_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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